

Method: Light Elements | PP4

3/7/2024 8:24:43 AM

Name: Lead frame Copper of After Cut Bend IC Micon.

Grade ID: No Match

Grade Alias:

Duration of measurement: 12.2 s (2.1/10.1)

Symbol	Zn / %	Sn / %	Pb / %	Al / %	Fe / %	Si / %	P / %	Se / %
Conc.	0.73	3.14	.040	3.43	20.8	12.8	0.52	.013
U	± 0.03	± 0.11	± .033	± 0.39	± 0.2	± 0.3	± 0.04	± .009

Symbol	Au / %	Sr / %	Ti / %	Mo / %	Cu / %			
Conc.	.081	.011	0.36	.012	58.0			
U	± .038	± .008	± 0.04	± .008	± 0.2			

Method: Light Elements | PP4

3/7/2024 8:23:58 AM

Name: Lead frame Copper of After Cut Bend IC Micon

Grade ID: No Match

Grade Alias:

Duration of measurement: 12.2 s (2.1/10.1)

Symbol	Zn / %	Sn / %	Ni / %	Al / %	Fe / %	Si / %	P / %	Cr / %
Conc.	0.17	5.39	.021	0.79	3.74	3.40	0.16	.015
U	± 0.03	± 0.17	± .016	± 0.39	± 0.06	± 0.15	± 0.03	± .014

Symbol	Se / %	Ti / %	Cu / %					
Conc.	.013	.093	86.2					
U	± .010	± .020	± 0.3					